APPLI-TEC
ADVANCED THERMOSET SOLUTIONS

5316

Key Features

Electrically Isolating
High Thermal Conductivity
Low Shrinkage
Flowable

Uncured

Pot Life @ 25°C: 1.5 hours
Viscosity, Mixed, @ 25°C: 12,500 cPs
Viscosity, Part A, @ 25°C: Paste
Viscosity, Part B, @ 25°C: 250 cPs
Shelf Life @ 25°C: 12 Months
Mix Ratio 100A : 5.6B Parts By Weight

Cure Options

24 hours @ 25° C
4 hours @ 65°C

Cured Properties

(Based on cure of 24 hours @ 25°C)

Color	Black
Shore D Hardness	85
Glass Transition Temp (°C)	55
Density (g/cc)	2.5
Lap Shear 2024T3 Clad (psi)	2,500

Product Description:

5316 is a room temperature curing, black, flowable, electrically isolating, thermally conductive epoxy designed specifically for underfilling, staking and encapsulating electronics on circuit boards as well as potting and encapsulating power supplies, transformers, and coils. This material features a long work life and is ideal for applications requiring a self leveling, thermal conductive epoxy with resistance to solvents and chemicals. 5316 is supplied as a 2 part room temperature storage kit. Contact customer service for pre-mix and frozen options.

Thermal Properties

(Based on cure of 24 hours @ 25°C)

Glass Transition Temp (°C)	55
Degradation Temp. (°C)	300
Thermal Conductivity (W/mK)	1.38

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